Preferred Device

### **Sensitive Gate Triacs**

#### **Silicon Bidirectional Thyristors**

Designed for use in solid state relays, MPU interface, TTL logic and any other light industrial or consumer application. Supplied in an inexpensive TO-92 package which is readily adaptable for use in automatic insertion equipment.

#### **Features**

- One-Piece, Injection-Molded Package
- Blocking Voltage to 600 Volts
- Sensitive Gate Triggering in Four Trigger Modes (Quadrants) for all possible Combinations of Trigger Sources, and especially for Circuits that Source Gate Drives
- All Diffused and Glassivated Junctions for Maximum Uniformity of Parameters and Reliability
- Pb-Free Packages are Available\*

#### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (T <sub>J</sub> = -40 to +110°C) (Note 1) Sine Wave 50 to 60 Hz, Gate Open MAC97A4 MAC97A6 MAC97A8	V <sub>DRM</sub> , V <sub>RRM</sub>	200 400 600	>
On-State RMS Current Full Cycle Sine Wave 50 to 60 Hz (T <sub>C</sub> = +50°C)	I <sub>T(RMS)</sub>	0.6	A
Peak Non-Repetitive Surge Current One Full Cycle, Sine Wave 60 Hz (T <sub>C</sub> = 110°C)	I <sub>TSM</sub>	8.0	Α
Circuit Fusing Considerations (t = 8.3 ms)	l <sup>2</sup> t	0.26	A <sup>2</sup> s
Peak Gate Voltage (t $\leq$ 2.0 $\mu$ s, T <sub>C</sub> = +80°C)	$V_{GM}$	5.0	V
Peak Gate Power (t $\leq$ 2.0 $\mu$ s, T <sub>C</sub> = +80°C)	$P_{GM}$	5.0	W
Average Gate Power $(T_C = 80^{\circ}C, t \le 8.3 \text{ ms})$	P <sub>G(AV)</sub>	0.1	W
Peak Gate Current (t $\leq 2.0 \mu\text{s},  \text{T}_{\text{C}} = +80^{\circ}\text{C}$ )	I <sub>GM</sub>	1.0	Α
Operating Junction Temperature Range	T <sub>J</sub>	-40 to +110	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



#### ON Semiconductor®

http://onsemi.com

# TRIACS 0.8 AMPERE RMS 200 thru 600 VOLTS



#### MARKING DIAGRAMS





MAC97Ax = Device Code
 x = 4, 6, or 8

A = Assembly Location
Y = Year
WW = Work Week

Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT			
1	Main Terminal 1		
2 Gate			
3	Main Terminal 2		

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### THERMAL CHARACTERISTICS

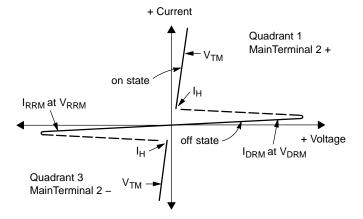
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	75	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	200	°C/W
Maximum Lead Temperature for Soldering Purposes for 10 Seconds	TL	260	°C

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

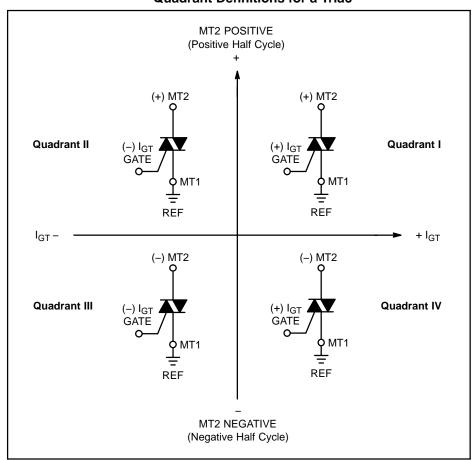
Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS			1	U.		Į.
Peak Repetitive Blocking Current (V <sub>D</sub> = Rated V <sub>DRM</sub> , V <sub>RRM</sub> ; Gate Open)	T <sub>J</sub> = 25°C T <sub>J</sub> = +110°C	I <sub>DRM</sub> , I <sub>RRM</sub>	_ _	_ _	10 100	μ <b>Α</b> μ <b>Α</b>
ON CHARACTERISTICS						
Peak On–State Voltage ( $I_{TM} = \pm .85$ A Peak; Pulse Width $\leq 2.0$ ms, Duty Cycle $\leq 2.0$ %)		$V_{TM}$	-	_	1.9	V
Gate Trigger Current (Continuous dc) $ (V_D=12\ Vdc,\ R_L=100\ \Omega) $ $ MT2(+),\ G(+) $ $ MT2(+),\ G(-) $ $ MT2(-),\ G(-) $ $ MT2(-),\ G(+) $		I <sub>GT</sub>	- - - -	- - - -	5.0 5.0 5.0 7.0	mA
Gate Trigger Voltage (Continuous dc) $ (V_D = 12 \text{ Vdc, R}_L = 100 \ \Omega) $ $ \text{MT2(+), G(+) All Types} $ $ \text{MT2(+), G(-) All Types} $ $ \text{MT2(-), G(-) All Types} $ $ \text{MT2(-), G(+) All Types} $ $ \text{MT2(-), G(+) All Types} $		V <sub>GT</sub>	- - - -	.66 .77 .84	2.0 2.0 2.0 2.5	V
Gate Non–Trigger Voltage ( $V_D$ = 12 V, $R_L$ = 100 $\Omega$ , $T_J$ = 110°C) All Four Quadrants		$V_{GD}$	0.1	-	-	V
Holding Current (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)		I <sub>H</sub>	-	1.5	10	mA
Turn-On Time $(V_D = Rated V_{DRM}, I_{TM} = 1.0 \text{ A pk}, I_G = 25 \text{ mA})$		t <sub>gt</sub>	-	2.0	-	μS
DYNAMIC CHARACTERISTICS	•		•	•	•	•
Critical Rate-of-Rise of Commutation Voltage ( $V_D$ = Rated $V_{DRM}$ , $I_{TM}$ = .84 A, Commutating di/dt = .3 A/ms, Gate Unenergized, $T_C$ = 50°C)		dV/dt(c)	_	5.0	_	V/µs
Critical Rate of Rise of Off–State Voltage $(V_D = Rated\ V_{DRM},\ T_C = 110^{\circ}C,\ Gate\ Open,\ Exponential\ Waveform$		dv/dt	-	25	-	V/μs

## Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current



#### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

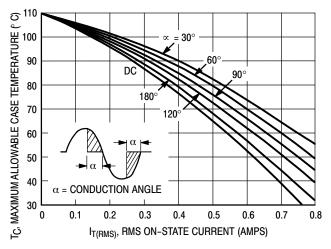


Figure 1. RMS Current Derating

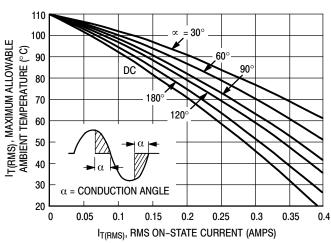


Figure 2. RMS Current Derating

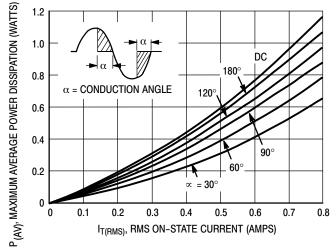


Figure 3. Power Dissipation

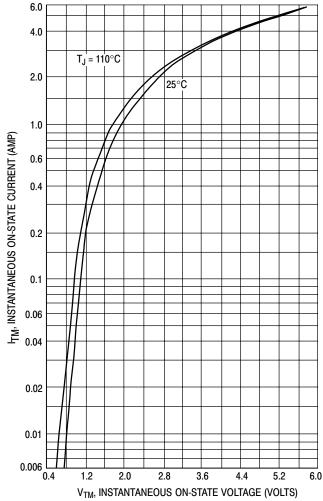
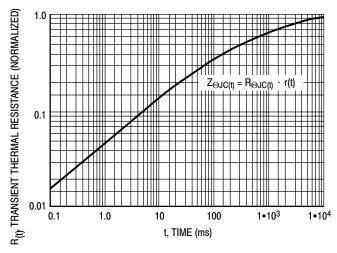


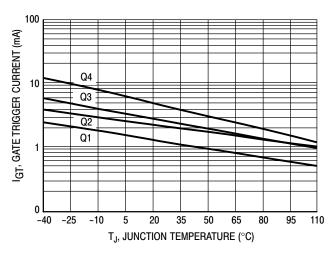
Figure 4. On-State Characteristics



10 TSM, PEAK SURGE CURRENT (AMPS) 5.0 3.0  $T_J = 110^{\circ}C$ 2.0 f = 60 Hz 1.0 1.0 2.0 3.0 10 30 50 100 5.0 NUMBER OF CYCLES

Figure 5. Transient Thermal Response

Figure 6. Maximum Allowable Surge Current



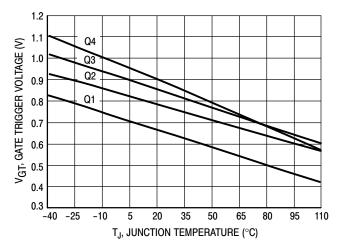
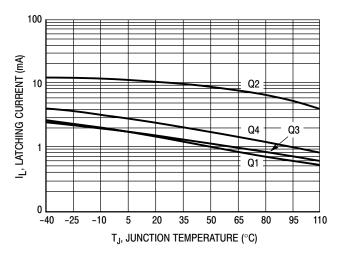


Figure 7. Typical Gate Trigger Current versus Junction Temperature

Figure 8. Typical Gate Trigger Voltage versus
Junction Temperature



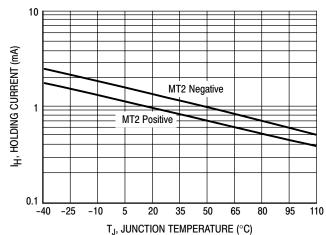
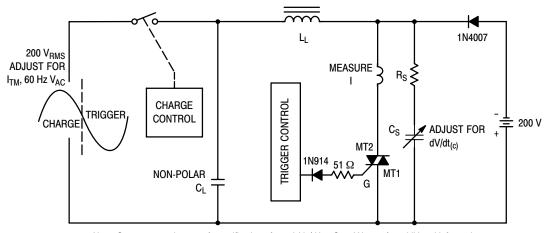


Figure 9. Typical Latching Current versus Junction Temperature

Figure 10. Typical Holding Current versus Junction Temperature



Note: Component values are for verification of rated (dv/dt)<sub>c</sub>. See AN1048 for additional information.

Figure 11. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Voltage (dV/dt)<sub>c</sub>

#### **ORDERING & SHIPPING INFORMATION**

U.S.	Europe Equivalent	Shipping	Description of TO92 Tape Orientation
	MAC97A6RL1	Radial Tape & Reel (2K/Reel)	Flat side of TO92 & adhesive tape visible
	MAC97A6RL1G	Radial Tape & Reel (2K/Reel) (Pb-Free)	Flat side of TO92 & adhesive tape visible
MAC97A8RLRM	MAC97A8RL1	Radial Tape & Reel (2K/Reel)	Flat side of TO92 & adhesive tape visible
MAC97A8RLRMG	MAC97A8RL1G	Radial Tape & Reel (2K/Reel) (Pb-Free)	Flat side of TO92 & adhesive tape visible
MAC97A4		Bulk in Box (5K/Box)	N/A, Bulk
MAC97A4G		Bulk in Box (5K/Box) (Pb-Free)	N/A, Bulk
MAC97A6		Bulk in Box (5K/Box)	N/A, Bulk
MAC97A6G		Bulk in Box (5K/Box) (Pb-Free)	N/A, Bulk
MAC97A8		Bulk in Box (5K/Box)	N/A, Bulk
MAC97A8G		Bulk in Box (5K/Box) (Pb-Free)	N/A, Bulk
MAC97A6RLRF		Radial Tape & Reel (2K/Reel)	Round side of TO92 & adhesive tape on reverse side
MAC97A6RLRFG		Radial Tape & Reel (2K/Reel) (Pb-Free)	Round side of TO92 & adhesive tape on reverse side
MAC97A6RLRP		Radial Tape & Reel (2K/Reel)	Round side of TO92 & adhesive tape on reverse side
MAC97A6RLRPG		Radial Tape & Reel (2K/Reel) (Pb-Free)	Round side of TO92 & adhesive tape on reverse side
MAC97A8RLRP		Radial Tape / Fan Fold Box (2K/Box)	Round side of TO92 & adhesive tape visible
MAC97A8RLRPG		Radial Tape / Fan Fold Box (2K/Box) (Pb–Free)	Round side of TO92 & adhesive tape visible

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### TO-92 EIA RADIAL TAPE IN FAN FOLD BOX OR ON REEL

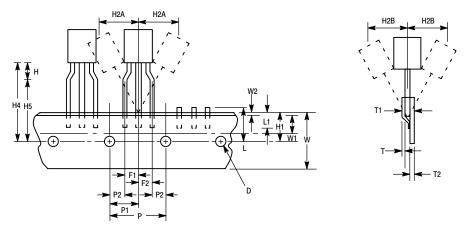


Figure 12. Device Positioning on Tape

		Specification			
		Inches		Millimeter	
Symbol	Item	Min	Max	Min	Max
D	Tape Feedhole Diameter	0.1496	0.1653	3.8	4.2
D2	Component Lead Thickness Dimension	0.015	0.020	0.38	0.51
F1, F2	Component Lead Pitch	0.0945	0.110	2.4	2.8
Н	Bottom of Component to Seating Plane	.059	0.156	1.5	4.0
H1	Feedhole Location	0.3346	0.3741	8.5	9.5
H2A	Deflection Left or Right	0	0.039	0	1.0
H2B	Deflection Front or Rear	0	0.051	0	1.0
H4	Feedhole to Bottom of Component	0.7086	0.768	18	19.5
H5	Feedhole to Seating Plane	0.610	0.649	15.5	16.5
L	Defective Unit Clipped Dimension	0.3346	0.433	8.5	11
L1	Lead Wire Enclosure	0.09842	_	2.5	_
Р	Feedhole Pitch	0.4921	0.5079	12.5	12.9
P1	Feedhole Center to Center Lead	0.2342	0.2658	5.95	6.75
P2	First Lead Spacing Dimension	0.1397	0.1556	3.55	3.95
Т	Adhesive Tape Thickness	0.06	0.08	0.15	0.20
T1	Overall Taped Package Thickness	_	0.0567	_	1.44
T2	Carrier Strip Thickness	0.014	0.027	0.35	0.65
W	Carrier Strip Width	0.6889	0.7481	17.5	19
W1	Adhesive Tape Width	0.2165	0.2841	5.5	6.3
W2	Adhesive Tape Position	0.0059	0.01968	0.15	0.5

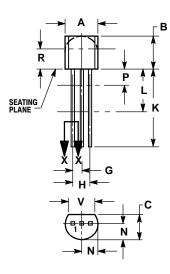
#### NOTES:

- 2. Maximum alignment deviation between leads not to be greater than 0.2 mm.
- 3. Defective components shall be clipped from the carrier tape such that the remaining protrusion (L) does not exceed a maximum of 11 mm.
- Component lead to tape adhesion must meet the pull test requirements.
- 5. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- 6. Holddown tape not to extend beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
- 7. No more than 1 consecutive missing component is permitted.
- 8. A tape trailer and leader, having at least three feed holes is required before the first and after the last component.
- 9. Splices will not interfere with the sprocket feed holes.

#### PACKAGE DIMENSIONS

#### TO-92 (TO-226AA)

CASE 029-11 **ISSUE AL** 





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R
  IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.175	0.205	4.45	5.20	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.045	0.055	1.15	1.39	
Н	0.095	0.105	2.42	2.66	
7	0.015	0.020	0.39	0.50	
K	0.500		12.70		
L	0.250		6.35		
N	0.080	0.105	2.04	2.66	
P		0.100		2.54	
R	0.115		2.93		
V	0.135		3.43		

STYLE 12: PIN 1. MAIN TERMINAL 1

- GATE
- MAIN TERMINAL 2

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